



Product Change Notification

113010 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 113010 - 00
Change Title: Intel® Integrated RAID Module
RMS25KB040 and RMS25KB080
PCN 113010-00, Product Design
Remove the R2B22 Resistor
Date of Publication: May 12, 2014

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material *:	Jun 05, 2014
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following change on the Intel® Integrated RAID Module RMS25KB080 and RMS25KB040:

- Remove the R2B22 pull-down resistor from the PRESENT# detection circuit on the RAID Module. The change will prevent the situation in which an additional PCIe* bridge device may be falsely recognized by the server system if the RAID Module is installed on the PCIe* slot which can support both the PCIe* adapter and riser. See Figure 1 below:

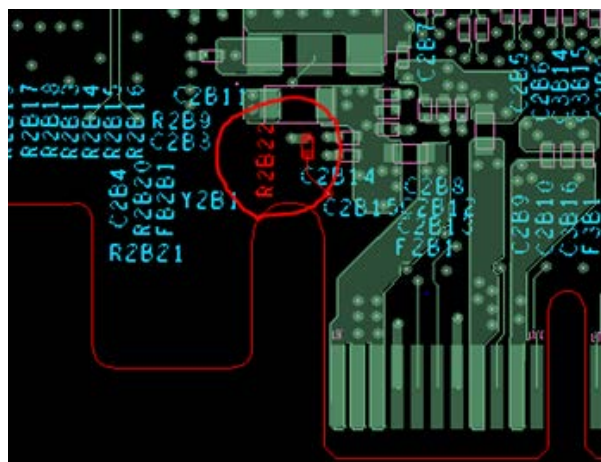


Figure 1. R2B22 pull-down resistor location

Customer Impact of Change and Recommended Action:

Intel expects no impact to customers from this change, but encourages the customers to understand the change and determine the impact on their applications, if any.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
RMS25KB080	924454	G34902-310	G35828-310	G34902-311	G35828-311
RMS25KB040	924455	G34903-310	G36694-310	G34903-311	G36694-311

PCN Revision History:

Date of Revision:

May 12, 2014

Revision Number:

00

Reason:

Originally Published PCN